

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) An electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member having an electrode in direct contact therewith, a metal member, and a bonding layer, said ceramic electrostatic chuck member and the said metal member being bonded with said bonding layer; wherein said bonding layer comprises at least a first outermost bonding layer bonded to said ceramic electrostatic chuck member, a second outermost bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost bonding layers, and wherein each of said first and second outermost bonding layers comprises a silicone layer.
2. (Currently Amended) The electrostatic chuck according to claim 1, wherein the thickness of said bonding layer is in a range of 0.05 to 0.5 mm.
3. (Currently Amended) The electrostatic chuck according to claim 1, wherein said ceramic electrostatic chuck member has comprises an aluminum nitride base material made of aluminum nitride, said base material is formed as an integrated body by sintering it said base material with an electrostatic chuck said electrode embedded therein.
4. (Currently Amended) The electrostatic chuck according to claim 1, wherein a flatness of an adsorption surface of said ceramic electrostatic chuck member is has a flatness of 30 μm or less.
5. (Currently Amended) A method for manufacturing an electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member having an

electrode in direct contact therewith, a metal member, and a bonding layer, said ceramic electrostatic chuck member and said metal member being bonded with said bonding layer, wherein said bonding layer has comprises at least a first outermost bonding layer bonded to said ceramic electrostatic chuck member, a second outermost bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost bonding layers, and wherein each of said first and second outermost bonding layers comprises a silicone layer, said method comprising the steps of:

providing said ceramic electrostatic chuck member;

providing said metal member;

preparing a sheet comprising at least said first outermost layer, said second outermost layer, and an intermediate layer disposed between said first and second outermost layers, said intermediate layer comprising said polyimide layer;

sandwiching said sheet between said ceramic electrostatic chuck member and said metal member;

vacuum-packing said ceramic electrostatic chuck member, said sandwiched sheet and said metal member into a vacuum-packing bag; and

heating the thus vacuum-packed ceramic electrostatic chuck member, sandwiched sheet and metal member under isotropic pressurization to bond them firmly.

6. (New) The electrostatic chuck according to claim 1, wherein said electrode is embedded in said ceramic electrostatic chuck member.

7. (New) The method according to claim 5, wherein said step of providing a ceramic electrostatic chuck member further comprises embedding said electrode in said ceramic electrostatic chuck member.

8. (New) An electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member, and a bonding layer bonding said

ceramic electrostatic chuck member and said metal member, said bonding layer comprising only a first outermost silicone bonding layer bonded to said ceramic electrostatic chuck member, a second outermost silicone bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost silicone bonding layers.

9. (New) The electrostatic chuck according to claim 8, further comprising an electrode embedded in said ceramic electrostatic chuck member.

10. (New) A method for manufacturing an electrostatic chuck having a bonded structure comprising a ceramic electrostatic chuck member, a metal member, and a bonding layer bonding said ceramic electrostatic chuck member and said metal member, said bonding layer comprising only a first outermost silicone bonding layer bonded to said ceramic electrostatic chuck member, a second outermost silicone bonding layer bonded to said metal member, and a polyimide layer disposed between said first and second outermost silicone bonding layers, said method comprising the steps of:

providing said ceramic electrostatic chuck member;

providing said metal member;

preparing a sheet comprising only said first outermost silicone bonding layer, said second outermost silicone bonding layer, and said polyimide layer disposed between said first and second outermost silicone bonding layers;

sandwiching said sheet between said ceramic electrostatic chuck member and said metal member;

vacuum-packing said ceramic electrostatic chuck member, said sandwiched sheet and said metal member into a vacuum-packing bag; and

heating the thus vacuum-packed ceramic electrostatic chuck member, sandwiched sheet and metal member under isotropic pressurization to bond them firmly.

11. (New) The method according to claim 10, wherein said step of providing a ceramic electrostatic chuck member further comprises embedding an electrode in said ceramic electrostatic chuck member.

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